

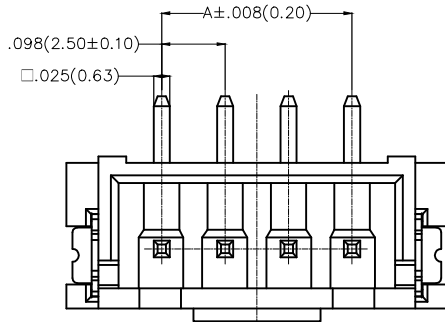
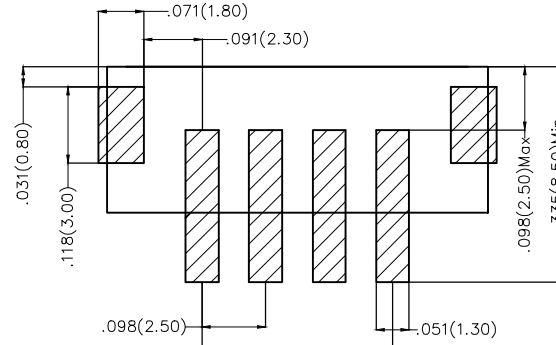
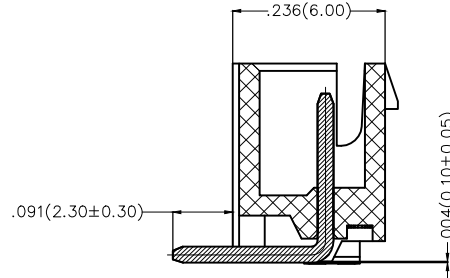
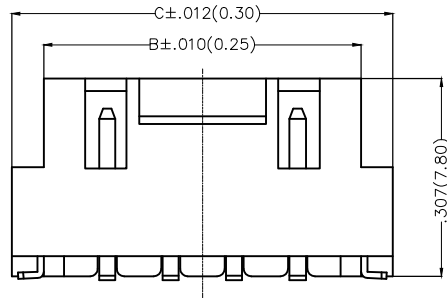
REV	LOCATIONS	DESCRIPTION	DATE	REVISOR	APPD

Electrical

Current Rating: 3A AC(rms)/DC
Voltage Rating: 250V AC(rms)/DC
Contact Resistance: 20 mΩ Max
Insulation Resistance: 1000 MΩ MIN
Withstanding Voltage: 1000V AC r.m.s
Temperature Range—Operating: -25°C~+85°C

Material and Plating

Housing: PA9T UL 94V-0
Contact Pin: Brass
Plating: Tin Plated
Solder Tab: Phosphor bronze



Recommended P.C.Board Layout

Ordering Information

FWF 250 29 — S XX S 2 5 W5 M
1 2 3 4 5 6 7 8 9 10

1	Category FWF—Wafer	2	Series Number 250—Pitch2.50mm	3	Distinction No. 29	4	Row Option S—Single Row	5	Circuits XX	6	Entry Angle S—180° Vertical
7	Plating 2—Tin Plated	8	Material—Resin 5—PA9T	9	Color—Resin W5—White	10	Packaging M—Reel				

 THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 06/JUN/17	PART NO. FWF25029—SXXS25W5M	ITEM NO. FWF25029	 Leader Of Industry		
	X. ±0.30	X.* ±5°	CHECKED BY CHERRY	DATE 06/JUN/17	TITLE Wire to Board (Wafer) Pitch 2.5mm 180° Vertical (SMT)			REV 0	SHEET NO. 1/2
	DESIGN UNITS Metric	X.X ±0.20	X.X* ±2°	DRAWN BY LXF	DATE 06/JUN/17	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
SCALE 5:1	SIZE A4	X.XX ±0.15	X.XX* ±1°						
		X.XXX ±0.10	X.XXX* ±0.5°						

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REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD

A

A

B

B

C

C

D

D

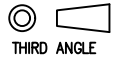

E

E

F

F

Circuits (n)	Part NO.	Dimension(in/mm)		
		A	B	C
2	FWF25029-S02S25W5M	.098(2.50)	.295(7.50)	.394(10.00)
3	FWF25029-S03S25W5M	.197(5.00)	.394(10.00)	.492(12.50)
4	FWF25029-S04S25W5M	.295(7.50)	.492(12.50)	.591(15.00)
5	FWF25029-S05S25W5M	.394(10.00)	.591(15.00)	.689(17.50)
6	FWF25029-S06S25W5M	.492(12.50)	.689(17.50)	.787(20.00)

 THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY	DATE	PART NO.	ITEM NO.	 Leader Of Industry
	X. ±0.30	X.* ±5'	FRANK	06/JUN/17	FWF25029-SXXS25W5M	FWF25029	
DESIGN UNITS Metric	X.X ±0.20	X.X' ±2'	CHECKED BY	DATE	TITLE		REV 0
SCALE	X.XX ±0.15	X.XX' ±1'	CHERRY	06/JUN/17	Wire to Board (Wafer) Pitch 2.5mm 180° Vertical (SMT)		
5:1	X.XXX ±0.10	X.XXX' ±0.5'	DRAWN BY	DATE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
A4			LXF	06/JUN/17			

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